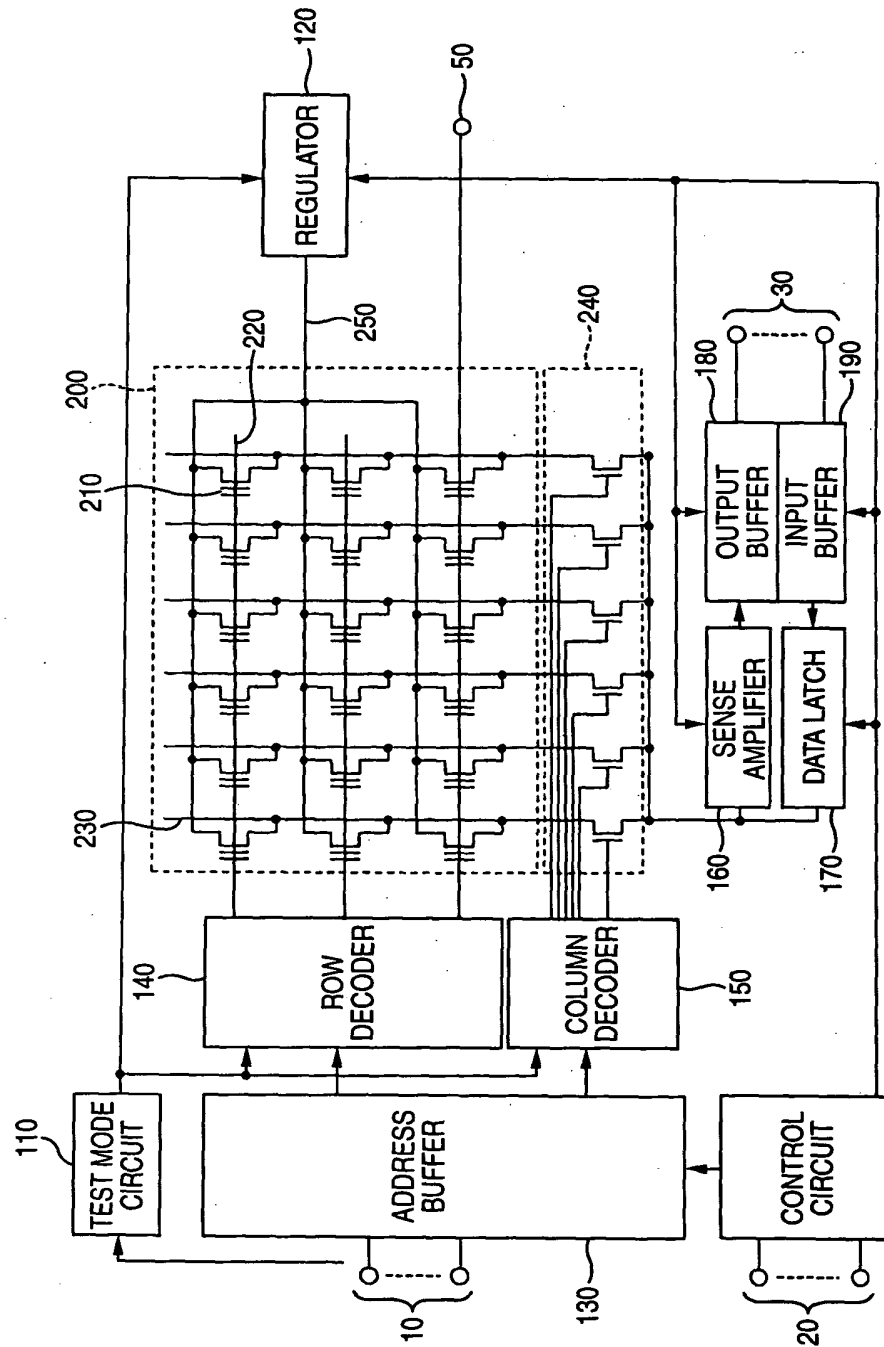


The diagram illustrates a semiconductor device 100 configured for test mode. Key components include a TEST MODE CIRCUIT 110, an ADDRESS BUFFER 130, a CONTROL CIRCUIT 100, a REGULATOR 120, a ROW DECODER 140, a COLUMN DECODER 150, and a memory array 200. The memory array 200 is composed of word lines 210, bit lines 220, and sense lines 230. A dashed box 240 highlights a specific region within the array. The array is interfaced with an OUTPUT BUFFER 180 and an INPUT BUFFER 190 through a SENSE AMPLIFIER 160 and a DATA LATCH 170. The device also features a TEST MODE CIRCUIT 110 and a REGULATOR 120. Various input/output pins are shown, including a group of pins 10, a group of pins 20, and a group of pins 30.

FIG. 2



[illegible]

FIG. 4

